Index page and overview

Page 2  Schematic

Page 3  Mechanical and Labels

Blockdiagram

V_IN  Shunt  Q1  Q2  V_OUT

LM5069  
OVLO, UVLO, OCP

LM5050  
Mis-Wire  
ReverseCurrent  
Protection

Shunt

V_IN  V_OUT

Q1  Q2

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Revision History

Revision  Notes

E1  First version of the board

Contact:  http://www.ti.com/support

Public Release

Rev:  E1

TIDA-00233

Sheet:  of 5
PCB Number: TIDA-00233
PCB Rev: E1

Power Protection for PLC
Project Title:
Designed for: Public Release
Assembly Variant: 002

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Drawn By: Engineer: Ingolf Frank

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This Assembly Note is for PCB labels only

These assemblies are ESD sensitive, ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>V2</td>
</tr>
<tr>
<td>002</td>
<td>V1</td>
</tr>
</tbody>
</table>

CO!PCB1 COFID1 COFID2 COFID3 COH2 COH3 COH5 COH6 COH8 COH9 COH11 COH12 COLBL1 COLogo1 COZZ1 COZZ2 COZZ3 COZZ4
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